CLAIMS

1. A method of manufacturing a flexible circuit incorporating a solid state light emitting component, the method comprising:

providing an insulating layer,

producing at least one through hole in the insulating layer,

providing a conductive layer,

bonding a main surface of the conductive layer to the insulating layer,

positioning at least one solid state light emitting component in the through hole of the insulating layer and connecting this component to the conductive layer;

wherein a portion of the flexible circuit comprises two contact pads and one thermal pad patterned in the conductive layer and partially covering said at least one through hole, the two contact pads spaced apart and separate from the thermal pad, and the at least one solid state light emitting component comprises contact pads and a thermal pad, said thermal pad of said at least one solid state light emitting component being connected to said one thermal pad patterned in the conductive layer.

2. The method according to claim 1, wherein the solid state light emitting component is a bare chip.

3. The method according to claim 1, wherein the step of producing at least one through hole in the insulating layer is performed preliminary to the bonding step so that the conductive layer covers the said at least one through hole of the insulating layer.

4. The method according to claim 1, wherein the conductive layer and the insulating layer are cut free from respective bands.

5. The method according to claim 1, wherein the connecting step comprises:

placing said at least one solid state light emitting component in said at least one through hole so that the contact pads and the thermal pad of the solid state component are connected with the conductive layer without wire-bonding.

6. The method according to claim 1, wherein the bonding and the through hole producing steps are performed repeatedly in at least one roll-to-roll apparatus.

7. The method according to claim 1, wherein an extended element is formed as a thermal pad patterned in the conductive layer which covers at least a portion of each thermal pad of different solid state light emitting components.

8. The method according to claim 1, wherein solid state light emitting components are connected in series with a track connecting to pads of adjacent solid state light emitting components, the track being insulated from a thermal track.

9. The method of claim 1, wherein a copper layer covers an upper side of the insulating layer which is opposite to a lower side of the insulating layer on which said conductive layer is bonded.

10. The method of claim 9, wherein an electroplating deposition is realized on the copper layer which covers an upper side of the insulating layer.

11. A flexible circuit incorporating a solid state light emitting component, the flexible circuit comprising an insulating layer, said insulating layer having two opposite sides and at least one through hole extending from one side to the other side of the insulating layer, the flexible circuit further comprising a conductive layer, a main surface of the conductive layer being bonded to the insulating layer, the solid state light emitting component being placed in the at least one through hole of the insulating layer and the solid state light emitting component being connected to the conductive layer, wherein the flexible circuit comprises two contact pads and one thermal pad patterned in the conductive layer and partially covering said at least one through hole, the two contact pads spaced apart and separate from the thermal pad, and the solid state light emitting component comprises two contact pads and a thermal pad, said thermal pad of said at least one solid state light emitting component being connected to said one thermal pad patterned in the conductive layer.